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PATENT

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2800 MAIL ROOM

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J. Wentz
(10/29/02)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Corisis et al.

Serial No.: 09/416,368

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

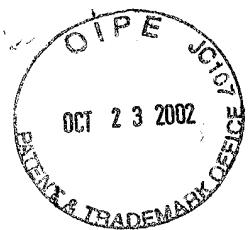
Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. The listed documents were cited by the office in co-pending application Serial No. 09/944,472, filed on August 30, 2001, and directed to a related invention. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as

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defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.



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U.S. Patent Documents

102800 MAIL ROOM

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
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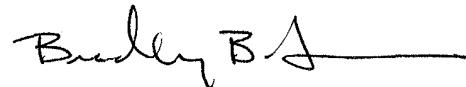
Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

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This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits.

The fee pursuant to 37 C.F.R. § 1.17(p) is enclosed.

Respectfully submitted,



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BBJ/hlg:djp

Enclosures: Form PTO-PTO/SB/08
Copy of documents cited

Document in ProLaw